

Title (en)
CHIP WITH A MICRO-ELECTROMECHANICAL STRUCTURE AND COVERING ELEMENT, AND A METHOD FOR THE PRODUCTION OF SAME

Title (de)
CHIP MIT MIKRO-ELEKTROMECHANISCHER STRUKTUR UND ABDECKUNGSELEMENT SOWIE VERFAHREN ZU DESSEN HERSTELLUNG

Title (fr)
PUCE À STRUCTURE MICRO-ÉLECTROMÉCANIQUE ET ÉLÉMENT DE RECOUVREMENT, ET PROCÉDÉ POUR SA FABRICATION

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Abstract (en)
[origin: WO2013075870A1] The invention relates to a micro-electromechanical chip (1) which comprises a substrate (1a), a micro-electromechanical structure (1b) formed in said substrate (1a), and a covering element (3) that is arranged on a surface of this substrate (1a) and that protects said micro-electromechanical structure (1b) from outside contaminants and/or mechanical influences.

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